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IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-07-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Representative Email *	Refer to Supplier Comment section		
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	2AJD*UQ55AD1	A	Z6RA	2016-07-07
Amount	UoM	Unit type	ST ECOPACK Grade	
6.85	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC105)	Tin/Silver/Copper (Sn/Ag/Cu)	NAC		

Package Designator	Size	Nbr of instances	Shape	
WAFER	2.62 - 2.279 - 0.35	30	bulk solder	
Comment	Package: CSPS0,4 26-100; MDF valid for STBC02BJR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	2AJD*UQ55AD1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.345	mg	supplier	die	Silicon (Si)	7440-21-3		4.869	mg	910945	711114
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.040	mg	7484	5842
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.032	mg	5987	4674
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	1497	1168
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.068	mg	12722	9931
Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.042	mg	7858	6134
Die				supplier	UBM	Copper (Cu)	7440-50-8		0.282	mg	52760	41186
Die				supplier	UBM	Titanium (Ti)	7440-32-6		0.004	mg	748	584
Bump	Solder	1.502	mg	supplier	bump	Tin (Sn)	7440-31-5		1.479	mg	984687	216007
Bump				supplier	bump	Silver (Ag)	7440-22-4		0.015	mg	9987	2191
Bump				supplier	bump	Copper (Cu)	7440-50-8		0.008	mg	5326	1168